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a [second substrate] motherboard having at least one contact;  
at least one solder ball extending between said at least one [first] substrate contact and  
said at least one [second substrate] motherboard contact, wherein said at least one solder ball is  
attached to one of said at least one [first] substrate contact and said at least one motherboard  
contact; and  
a compression mechanism for imparting pressure between said [first] substrate and said  
[second substrate] motherboard.

2. (First Amended) The microelectronic component assembly of claim 1, wherein said  
[first] substrate comprises a microelectronic device package.

4. (First Amended) The microelectronic component assembly of claim 1, wherein said  
[first] substrate comprises a microelectronic device.

B2  
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5. (First Amended) The microelectronic component assembly of claim 1, wherein said  
solder ball is attached to said at least one substrate contact and at least one [second substrate]  
motherboard contact comprises a recess defined by at least one sidewall extending into said  
[second substrate] motherboard.

6. (First Amended) The microelectronic component assembly of claim 5, wherein said  
at least one recessed [second substrate] motherboard contact includes a width which is  
substantially the same as a diameter of said solder ball.

B2  
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7. (First Amended) The microelectronic component assembly of claim 5, wherein said at least one recessed [second substrate] motherboard contact has a semispherical surface which is substantially the same radius as a radius of said solder ball.

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12. (First Amended) A microelectronic component assembly, comprising:

- a [first] substrate having a first surface and a second surface, wherein said first substrate first surface includes at least one contact;
- a [second substrate] motherboard having a first surface and a second surface; wherein said [second substrate] motherboard first surface includes at least one contact;
- at least one solder ball extending between said at least one [first] substrate first surface contact and said at least one [second substrate] motherboard first surface contact, wherein said at least one solder ball is attached to one of said at least one [first] substrate first surface contact and said at least one [second substrate] motherboard first surface contact; and
- a support structure for imparting pressure between said [first] substrate and said [second substrate] motherboard.

13. (First Amended) The microelectronic component assembly of claim 12, wherein said support structure comprises:

- a frame surrounding a portion of said [first] substrate,
- a backing plate abutting said [second substrate second surface] motherboard;
- a thermal plate extending over said frame and adjacent said [first] substrate second

surface; and

a plurality of retention devices extending through said backing plate, said frame, and said thermal plate.

B3  
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15. (First Amended) The microelectronic component assembly of claim 12, wherein said [first] substrate comprises a microelectronic device package including a microelectronic device attached to and in electrical contact with a first surface of an interposer substrate, and wherein said at least [first] substrate first surface contact comprises at least one contact on a second surface of said interposer substrate.

B4

16. (First Amended) The microelectronic component assembly of claim 15, wherein said support frame comprises

a frame surrounding a portion of said [first] substrate,  
a backing plate abutting said [second substrate] motherboard second surface;  
a thermal plate extending over said frame and adjacent said [first] substrate second surface;  
a plurality of retention devices extending through said backing plate, said frame[,], and the thermal plate; and  
a resilient spacer extending between said thermal plate and said interposer substrate.

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23. (First Amended) A substrate contact for forming a non-reflow electrical contact with a solder ball, comprising:

B5

a recess [define] defined in a substrate by at least one surface extending into said substrate having at least one substantially vertical side wall; and

a conductive material layered in said recess, wherein said conductive material is also layered on said at least one substantially vertical side wall.

B6

25. (First Amended) The substrate contact of claim [24] 23, further including a width of said recess, including said layered conductive material, which is substantially the same as a diameter of said solder ball.

B7

[27] 28. (First Amended) A substrate contact for forming a non-reflow electrical contact with a solder ball, comprising:

a recess define in a substrate by at least one surface extending into said substrate; and  
a conductive material layered over said recess forming a void in said recess.

(Please add claims 29-33, as follows:)

B8  
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-- 29. The microelectronic component assembly of claim 1, wherein said solder ball is attached to said motherboard contact and at least one substrate contact comprises a recess defined by at least one sidewall extending into said substrate.

30. The microelectronic component assembly of claim 29, wherein said at least one recessed substrate contact includes a width which is substantially the same as a diameter of said solder ball.

31. The microelectronic component assembly of claim 29, wherein said at least one recessed substrate contact has a semispherical surface which is substantially the same radius as a radius of said solder ball.

32. A substrate contact for forming a non-reflow electrical contact with a solder ball, comprising:

a semispherical recess defined in a substrate by at least one surface extending into said substrate;

a conductive material layered in said semispherical recess; and

an upper surface of said conductive material layer having a radius which is substantially the same as a radius of said solder ball.

33. The substrate contact of claim 32, further including a resilient material disposed between said substrate and said conductive material layer. --

Please cancel claims 3, 8-11, 17-22, 24, 26 (previously misnumbered as claim 25), and 27 (previously misnumbered as claim 26), without prejudice.

#### REMARKS

Claims 1, 2, 4-7, 12-16, 23, 25, and 28-33 remain in the application. Claims 1, 2, 4-7, 12, 13, 15, 16, 23, 25, and 28 (previously misnumbered as claim 27) have been amended. Claim 8-11 and 17-22 have been canceled without prejudice. The originally filed application was filed